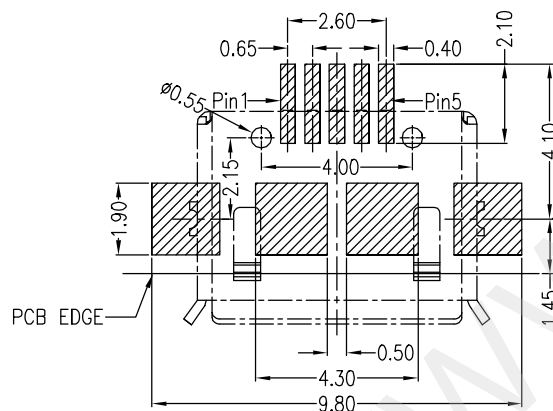
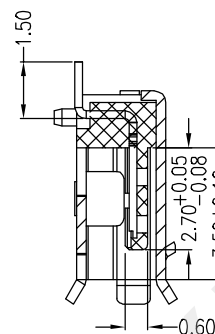
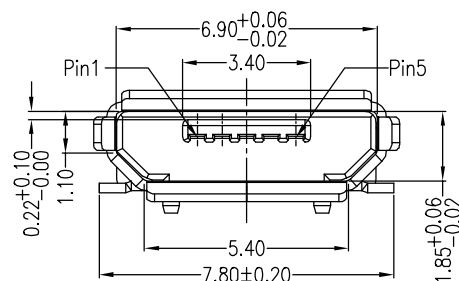
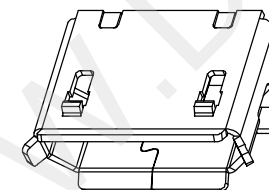
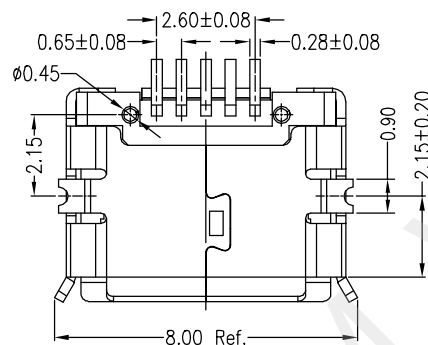
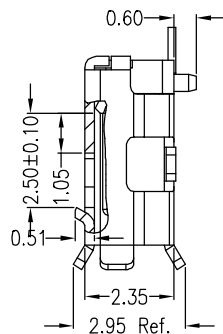
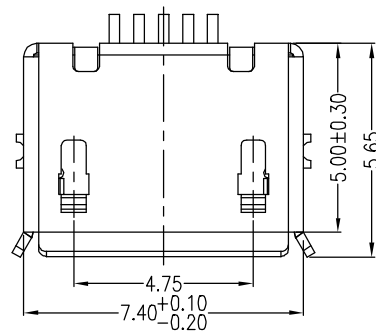
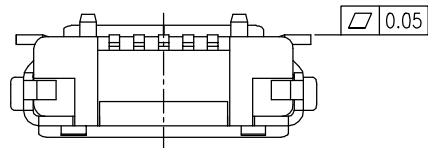




Note:

1.Material:

- 1.1 Housing: High temperature thermoplastic with g.f,UL94v-0
- 1.2 Contact: copper alloy,t=0.20mm
- 1.3 Shell: copper alloy,t=0.25mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 100 V(ac) for 1 min.
- 2.3 Contact resistance: 50 mW Max.
- 2.4 Insulation resistance: 100 MW Min.
- 2.5 Total mating force: 3.57 Kgf Max.
- 2.6 Total unmating force: 1.0 Kgf Min.0.81~2.05 Kgf Min.
- 2.7 Temperature range: -30°C~80°C



深圳市华宇创精密电子有限公司

TOLERANCE:

X.X ±0.30
X.XX ±0.25
X.XXX ±0.15

X' ±2° X.X' ±0.5°



UNIT: mm [inch]

SCALE:1:1

SIZE: A4

DRAWN BY :

陈一鸣

DATE :

2014-02-23

CHECKED BY:

马跃

DATE :

2014-02-23

APPROVED BY:

邱敏

DATE :

2014-02-23

PART NAME: MICRO USB 5P B口

全贴片 有柱有卷边 针加长0.75

PART NO.

HYC351-USBD05-150

MOLD NO.

DRAW NO:

HYC-2601201545

SHEET NO.

1 OF 1